

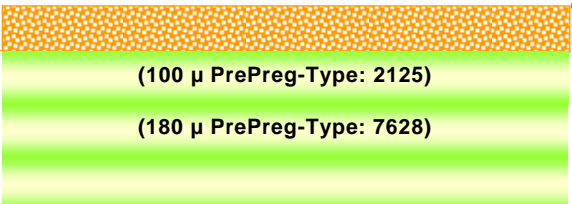
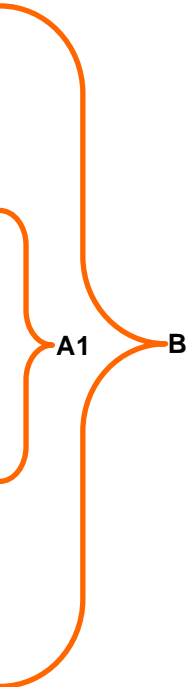
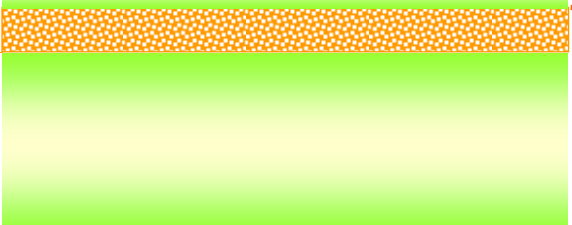
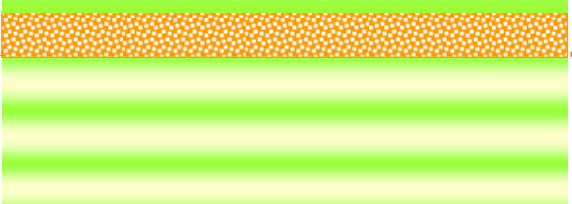

**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**04 260 FR4 55 L150.35 P18\_10 S1**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_260\_FR4\_55\_L150.35\_p18\_10\_s1**

Layers	in $\mu$	Material	Build-Up	Assembly	
<b>Layer-1</b>	55 $\mu$	Copper			
	100 $\mu$	Prepreg			(100 $\mu$ PrePreg-Type: 2125)
	180 $\mu$	Prepreg			(180 $\mu$ PrePreg-Type: 7628)
	180 $\mu$	Prepreg			
<b>Layer-2</b>	35 $\mu$	Copper			
	1500 $\mu$	L-FR4			
<b>Layer-3</b>	35 $\mu$	Copper			
	180 $\mu$	Prepreg			
	180 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
<b>Layer-99</b>	55 $\mu$	Copper			

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